

INTRODUCTION

GLT - S98 is a two-component silicone, low viscosity, good bonding future, shelf leveling design for electronics potting applications. This material cures at room temperature to a soft, flexibility, provides excellent protection for electronic assemblies from external humidity, mechanical shock and vibration.

FEATURES

- Convenient 1:1 mix ratio by weight
- Low viscosity - easily pourable
- Soft, flexibility
- Room temperature curable
- Excellent electrical properties
- Low shrinkage
- No reactive by-products; non corrosive
- Temperature resistance range is -60~200°C.
- Good yellowing resistance and weather resistance.
- Absorbs shock and protects delicate mechanical components from vibration

TYPICAL UNCURED PROPERTIES

	GLT- S98
Appearance	Liquid
Color	Transparent
Viscosity(cps)	600
Specific Gravity(g/cm ³)	1.05-1.10

STORAGE AND SHELF LIFE

It should be storage in cool and dark place in order to prevent the resin and hardener will become yellow under sunshine. This product is amine content, replace lid immediately after use. Keep without any possibility of wet when not using. This product has a two year minimum shelf life when stored below 14~34°C in original, unopened containers

CAUTION

Adhesive contact with skin is likely to produce mild transient reddening. It is important to remove adhesive from skin with soap and water thoroughly. DO NOT use solvents for cleaning hands. This product is of moderate acute toxicity by swallowing. If swallowed, call a physician. Avoid contact with eyes. In case of contact, flush with water for at least 15 minutes and get medical attention immediately. For more information, refer to the Material Safety Data Sheet.

DIRECTION FOR USE

1. The resin should be applied to a clean surface which is free of dirt, grease or mold release. In many cases, a simple solvent wipe is sufficient.
2. Before use, first mix component A well
3. Mix thoroughly by weight 1:1 . Mix approximately 15 seconds after uniform color is obtained.
4. Weight the correct proportions to within 2% accuracy and mix thoroughly together, scraping both the bottom and the sides of mixing container, until a homogeneous mixture is obtained.
5. Cure time on the really part will depend upon factors such as part geometry, materials to be bonded, bondline thickness and efficiency of the oven. Cure schedule should be confirmed with actual production parts and equipment.

TYPICAL UNCURED PROPERTIES

Mix Rate (A:B) By Weight	1:1
Pot Life, 25°C, min	40-60
Through Cure Time, 25°C, days	10
A:B=4g:1g	

TYPICAL UNCURED PROPERTIES

Hardness (shore A)	25±2
Thermal conductivity (W (m·K))	0.2 - 0.3
Working temperature (C)	-60 to 200
Dielectric strength (kV/mm)	25
Dielectric permittivity (1.2MHz)	~3.2
Volume resistivity (Ω·cm)	10 ¹⁵ ~10 ¹⁶
Fire resistance	UL9
Specific gravity (g/cm ³)	1.05 ~ 1.10